



Specification of Automotive MLCC

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10C470FB81PNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 47pF, 50V, ±1%, C0G, 0603

• AEC-Q 200 Specified

A. Samsung Part Number

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1	Series	Samsung Multi-layer Ceramic Capacitor				
2	Size	0603 (inch code)	L:	1.6 ± 0.1 mm	W: 0.8 ± 0.1	mm
3	Dielectric	C0G	(8 Inner electrode	Ni	
4	Capacitance	47 pF		Termination	Cu	
(5)	Capacitance	±1 %		Plating	Sn 100%	(Pb Free)
	tolerance		(9 Product	Automotive	
6	Rated Voltage	50 V	(Grade code	Standard	
7	Thickness	0.8 ± 0.1 mm	(Packaging	Cardboard Typ	e, 7" reel(4,000ea)

B. Reliability Test and Judgement condition

	Performance	Test condition	
High Temperature	Appearance : No abnormal exterior appearance	Unpowered, 1000hrs@T=150°C	
Exposure	Capacitance Change :	Measurement at 24±2hrs after test conclusion	
	within ±2.5% or ±0.25pF whichever is larger		
	Q: 1000 min		
	IR : More than 10,000№ or 500№×μF		
	Whichever is Smaller		
Temperature Cycling	Appearance : No abnormal exterior appearance	1000Cycles	
	Capacitance Change :	Measurement at 24±2hrs after test conclusion	
	within ±2.5% or ±0.25pF whichever is larger	1 cycle condition :	
	Q: 1000 min	-55+0/-3 ℃ (15±3min) -> Room Temp(1min.)	
	IR : More than 10,000№ or 500№×μF	-> 125+3/-0 °C (15±3min) -> Room Temp(1min.)	
	Whichever is Smaller		
Destructive Physical No Defects or abnormalities		Per EIA 469	
Analysis			
Moisture Resistance	Appearance : No abnormal exterior appearance	10Cycles, t=24hrs/cycle	
	Capacitance Change :	Heat (25~65 °C) and humidity (80~98%), Unpowered	
	within ±2.5% or ±0.25pF whichever is larger	measurement at 24±2hrs after test conclusion	
	Q: 350 min		
	IR : More than 10,000MΩ or 500MΩ×μF		
	Whichever is Smaller		
Humidity Bias	Appearance : No abnormal exterior appearance	1000hrs 85 ℃/85%RH, Rated Voltate and 1.3~1.5V,	
	Capacitance Change :	Add 100kohm resistor	
	within ±2.5% or ±0.25pF whichever is larger	Measurement at 24±2hrs after test conclusion	
	Q: 200 min	The charge/discharge current is less than 50mA.	
	IR : More than 500MΩ or 25MΩ×μF		
	Whichever is Smaller		
High Temperature	Appearance : No abnormal exterior appearance	1000hrs @ TA=125℃, 200% Rated Voltage,	
Operating Life	Capacitance Change :	Measurement at 24±2hrs after test conclusion	
	within ±3.0% or ±0.3pF whichever is larger	The charge/discharge current is less than 50mA.	
	Q: 350 min		
	IR : More than 10,000MΩ or 500MΩ×μF		
	Whichever is Smaller		

	Performance	Test condition	
External Visual	No abnormal exterior appearance	Microscope ('10)	
Physical Dimensions	Within the specified dimensions	Using The calipers	
Mechanical Shock	Appearance : No abnormal exterior appearance	Three shocks in each direction should be applied along	
	Capacitance Change :	3 mutually perpendicular axes of the test specimen (18 shocks)	
	within ±2.5% or ±0.25pF whichever is larger	Peakvalue Duration Wave Velocity	
	Q, IR: initial spec.	1,500G 0.5ms Half sine 4.7m/sec.	
Vibration	Appearance : No abnormal exterior appearance	5g's for 20min., 12cycles each of 3 orientations,	
	Capacitance Change :	Use 8"x5" PCB 0.031" Thick 7 secure points on one long side	
	within ±2.5% or ±0.25pF whichever is larger	and 2 secure points at corners of opposite sides. Parts mounted	
	Q, IR : initial spec.	within 2" from any secure point. Test from 10~2000Hz.	
Resistance to	Appearance : No abnormal exterior appearance	Solder pot : 260±5 ℃, 10±1sec.	
Solder Heat	Capacitance Change :		
	within ±2.5% or ±0.25pF whichever is larger		
	Q, IR : initial spec.		
Thermal Shock	Appearance : No abnormal exterior appearance	-55 ℃/+125 ℃.	
	Capacitance Change :	Note: Number of cycles required-300,	
	within ±2.5% or ±0.25pF whichever is larger	Maximum transfer time-20 sec, Dwell time-15min. Air-Air	
	Q, IR: initial spec.		
ESD	Appearance : No abnormal exterior appearance	AEC-Q200-002	
	Capacitance Change :		
	within ±2.5% or ±0.25pF whichever is larger		
	Q, IR : initial spec.		
Solderability	95% of the terminations is to be soldered	a) Preheat at 155 ℃ for 4 hours, Immerse in solder for 5s at 245±5 ℃	
	evenly and continuously	b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5 °C	
		c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5 °C	
		solder : a solution ethanol and rosin	
Electrical	Capacitance : Within specified tolerance	The Capacitance /Q should be measured at 25 ℃,	
Characterization	Q: 1000 max.	1Mb±10%, 0.5~5Vrms	
	IR(25 °C): More than 100,000 MΩ or 1,000 MΩ×μF	I.R. should be measured with a DC voltage not exceeding	
	IR(125℃) : More than10,000MΩ or 100MΩ×μF	Rated Voltage @25°C, @125°C for 60~120 sec.	
	Whichever is Smaller	Dielectric Strength: 250% of the rated voltage for 1~5 seconds	
Board Flex	Dielectric Strength	Danding to the limit (2) \ for E accords	
Board Flex	Appearance : No abnormal exterior appearance	Bending to the limit (3mm) for 5 seconds	
	Capacitance Change :		
Terminal	within ±5.0% or ±0.5pF whichever is larger Appearance: No abnormal exterior appearance	10N, for 60±1 sec.	
Strength(SMD) Capacitance Change:		1014, 101 00±1 350.	
Strength(SMD)	within ±2.5% or ±0.25pF whichever is larger		
Beam Load	Destruction value should not be exceed	Beam speed	
Stall Load	Chip Length < 2.5mm	0.5±0.05mm/sec	
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	a) Chip Thickness > 0.5mm : 20N		
Temperature	b) Chip Thickness ≤ 0.5mm : 8N COG		
Characteristics	(From -55℃ to 125℃, Capacitance change should	he within +30PPM/℃)	
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C. Recommended Soldering method :

Meet IPC/JEDEC J-STD-020 D Standard

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.